

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	360	"15" and "wet bench"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:32
L2	153	1 and tank	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:32
L3	67	2 and spray	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:32
L4	0	3 and modulus	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:32
L5	1	1 and modulus	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:32
S1	162412	modulus	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:45
S2	1	S1 and "semiconductor manufacturing"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:45
S3	448	S1 and "assembly line"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:45
S4	195	S3 and determine	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46
S5	471	modulus near determine	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46
S6	5268	modulus same determine	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46
S7	1	S5 and S4	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46

S8	14122	S1 and remainder	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46
S9	118	S8 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:46
S10	85	S9 and determine	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:48
S11	10079	S8 not elasticity	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:48
S12	81	S11 and S3	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 09:48
S13	62	S12 and determine	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 11:04
S14	12857	semiconductor and tank and processing	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 11:04
S15	1072	S14 and liquid and batch and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 11:04
S16	30	S15 and "semiconductor manufacturing facility"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/05/17 16:31